

BRCM24C08SC

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+' ' B_q

HBM mode Pinning

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/ Marking

/ Reliability Characteristic

BRCM24C08SC

/ Functional Description

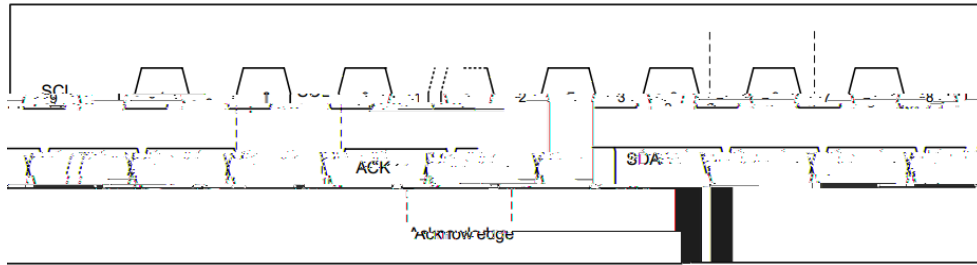


图 10 待机模式下的时序图

/ Standby Mode

9I : D) +: ' / J: $\bar{X}\bar{Z}$ $\bar{Y}\bar{Z}$
#ZZ

/ Soft Reset

#ZZ + $\bar{X}\bar{Z}$ $\bar{Y}\bar{Z}$

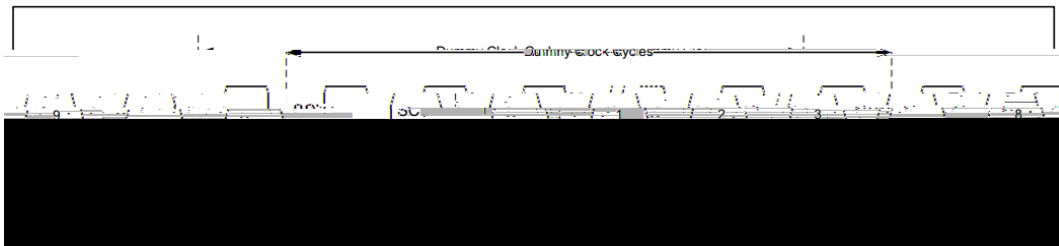


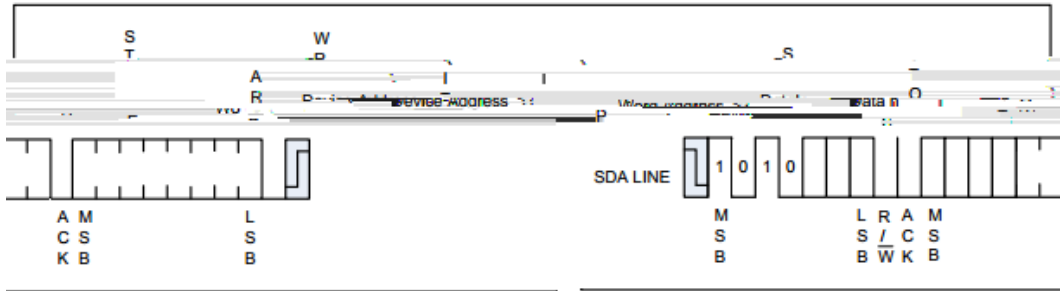
图 11 设备寻址时的时序图

/ Device Addressing

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/ Functional Description

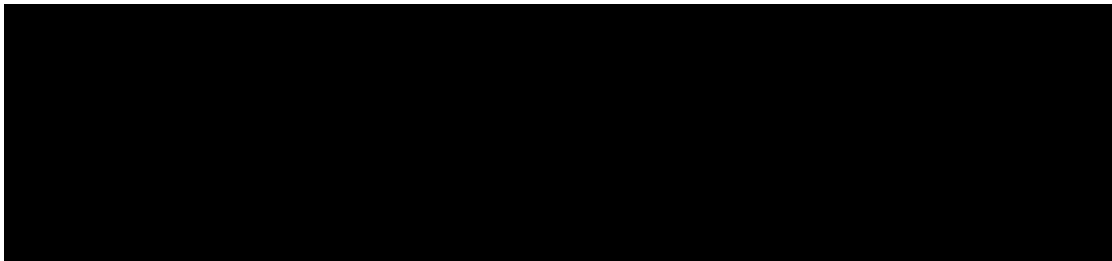
/ Functional Description



/ Page Write

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9l : D) + : ' / J :



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9l : D) + : ' / J :

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/ Functional Description

/ Acknowledge Polling

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& 9l : D) +: ' /J:

/ Write Identification Page

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/ Lock Identification Page

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/ Functional Description

/ Read Operations

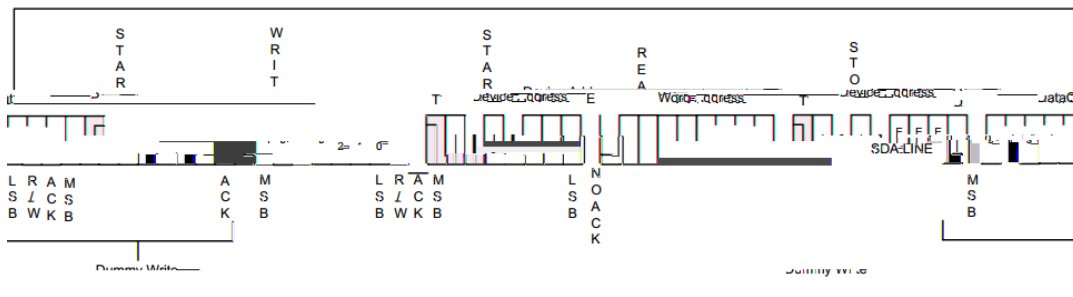
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/ Functional Description



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/ Functional Description

/ Read Identification Page

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/ Functional Description

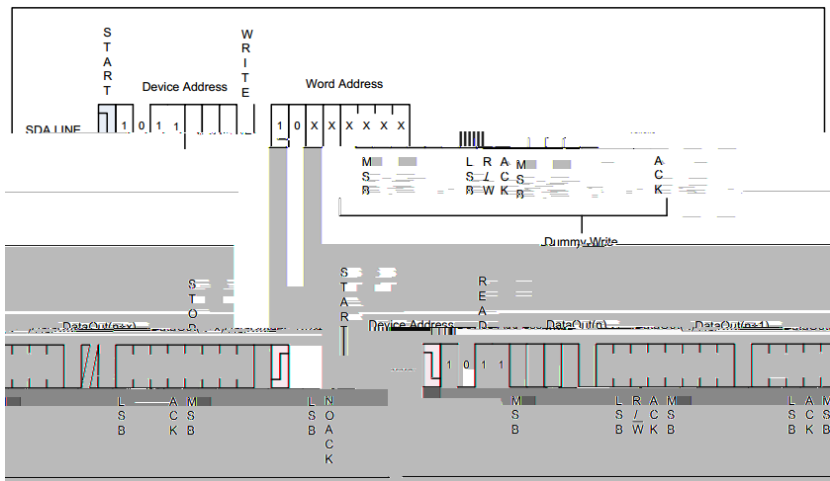
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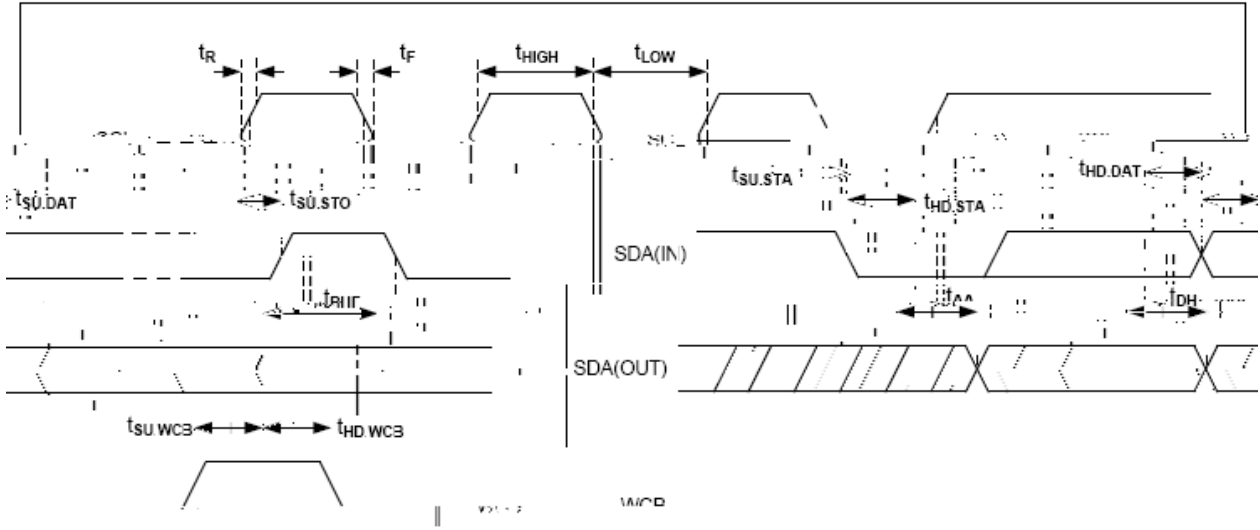
8: B



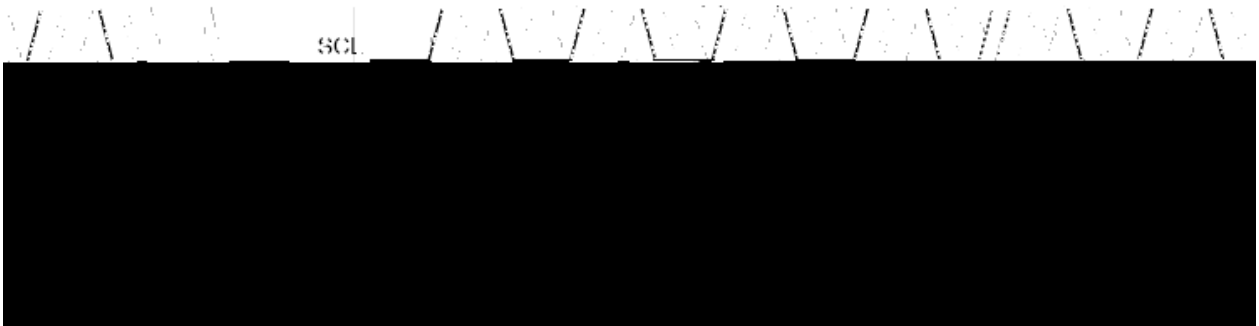
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/ Time Sequence Diagram

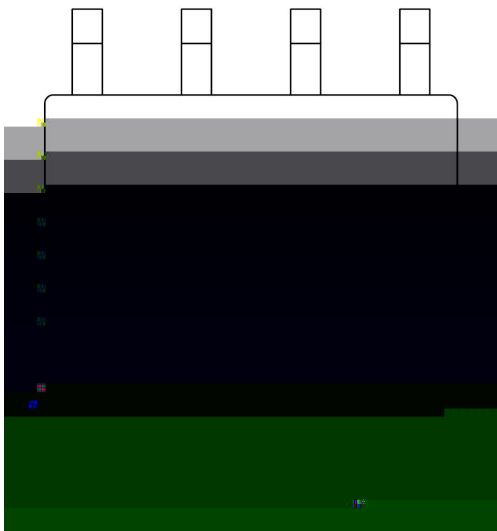
Bus Timing



Write Cycle Timing

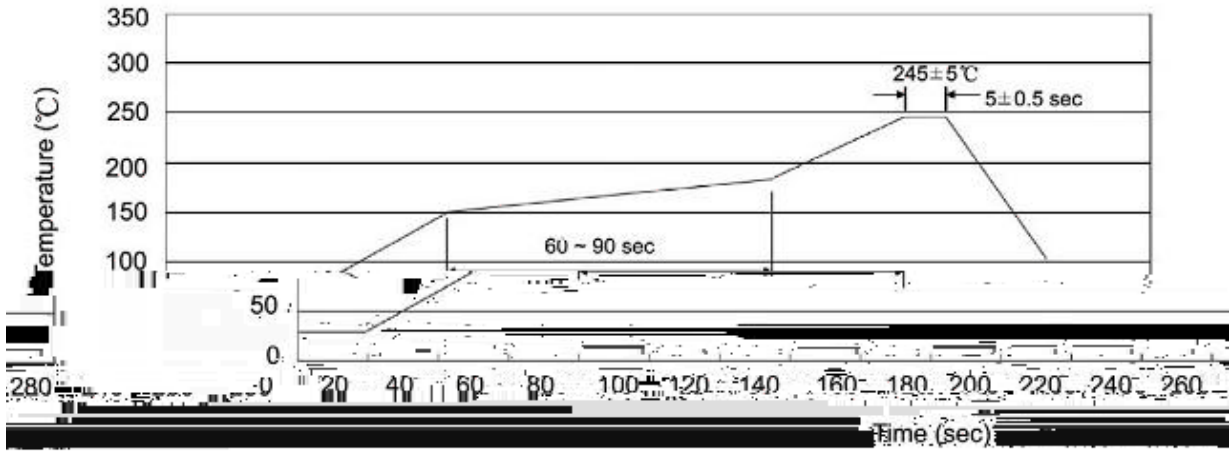


/ Marking Instructions



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() / Temperature Profile for IR Reflow Soldering(Pb-Free)



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/ Resistance to Soldering Heat Test Conditions



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